

# MEMORY Mobile FCRAM™

CMOS

## 16 Mbit (1 M word × 16 bit)

### Mobile Phone Application Specific Memory

# MB82D01171A-80/80L/80LL/85/85L/85LL/90/90L/90LL

CMOS 1,048,576-WORD × 16 BIT  
Fast Cycle Random Access Memory  
with Low Power SRAM Interface

#### DESCRIPTION

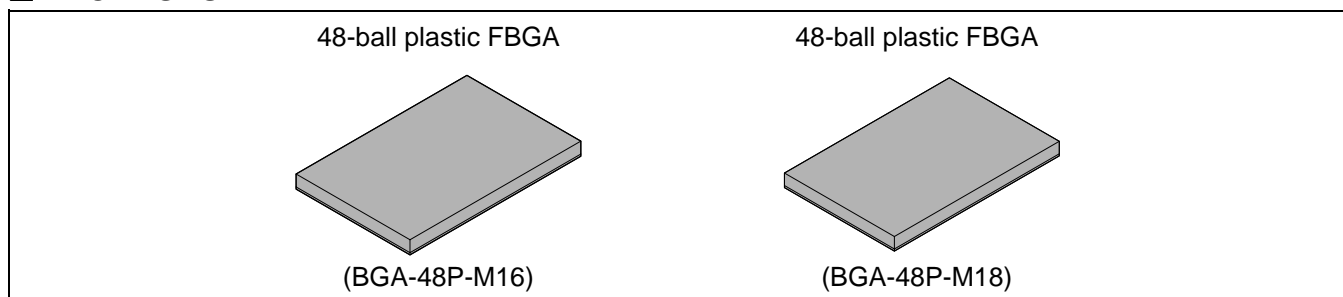
The Fujitsu MB82D01171A is a CMOS Fast Cycle Random Access Memory (FCRAM) with asynchronous Static Random Access Memory (SRAM) interface containing 16,777,216 storages accessible in a 16-bit format. This MB82D01171A is suited for low power applications such as Cellular Handset and PDA.

Note: FCRAM is a trademark of Fujitsu Limited, Japan.

#### PRODUCT LINEUP

Parameter	MB82D01171A								
	80	80L	80LL	85	85L	85LL	90	90L	90LL
Access Time (t <sub>AA</sub> Max, t <sub>CE</sub> Max)	80 ns			85 ns			90 ns		
Active Current (I <sub>DDA1</sub> Max)	20 mA								
Standby Current (I <sub>DDs1</sub> Max)	200 μA	100 μA	70 μA	200 μA	100 μA	70 μA	200 μA	100 μA	70 μA
Power Down Current (I <sub>DDP</sub> Max)	10 μA								

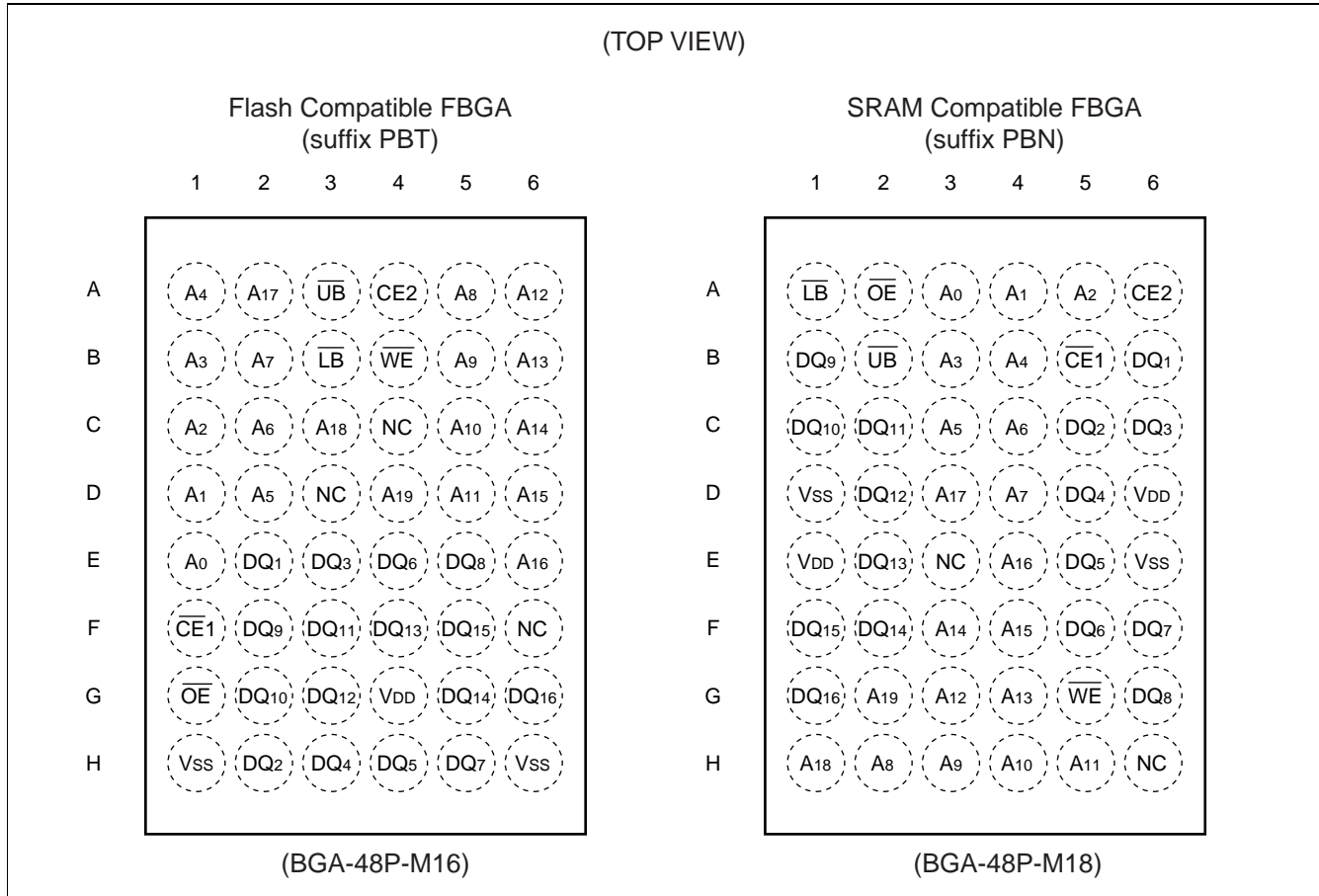
#### PACKAGES



## ■ FEATURES

- Asynchronous SRAM Interface
- 1 M word × 16 bit Organization
- Fast Random Cycle Time :  $t_{RC} = 90$  ns
- Fast Random Access Time :  $t_{AA} = t_{CE} = 80$  ns, 85 ns, 90 ns
- Low Power Consumption :  $I_{DDs1} = 200$   $\mu$ A, 100  $\mu$ A (L version) , 70  $\mu$ A (LL version)
- Wide Operating Conditions :  $V_{DD} = +2.3$  V to +2.7 V  
+2.7 V to +3.1 V  
+3.1 V to +3.5 V  
 $T_A = -30$  °C to +85 °C
- Byte Write Control
- 4 words Address Access Capability
- Power Down Control by CE2

## ■ PIN ASSIGNMENTS

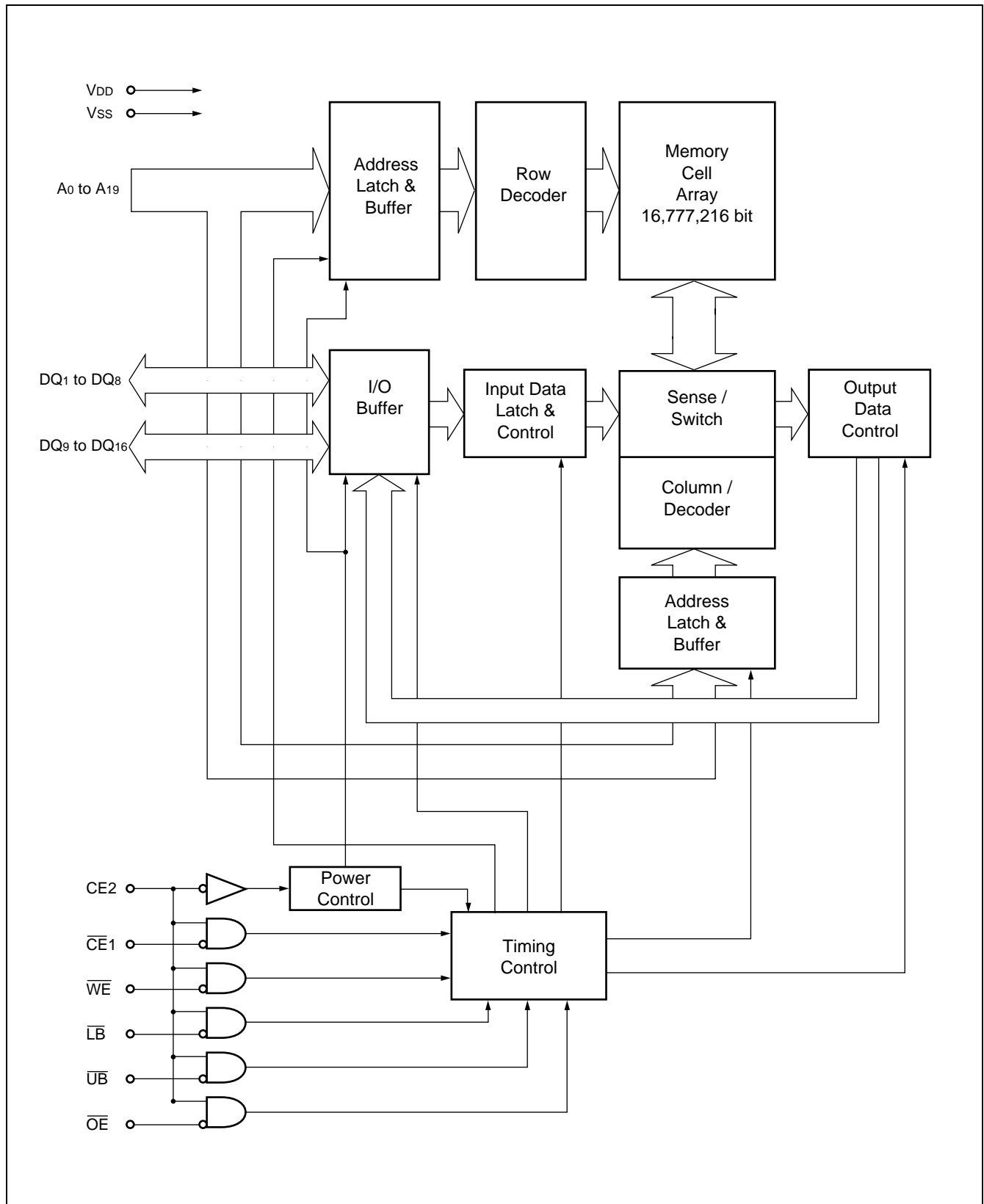


## ■ PIN DESCRIPTION

Pin Name	Description
A <sub>0</sub> to A <sub>19</sub>	Address Input
$\overline{CE1}$	Chip Enable (Low Active)
CE2	Chip Enable (High Active)
$\overline{WE}$	Write Enable (Low Active)
$\overline{OE}$	Output Enable (Low Active)
$\overline{LB}$	Lower Byte Write Control (Low Active)
$\overline{UB}$	Upper Byte Write Control (Low Active)
DQ <sub>1</sub> to DQ <sub>8</sub>	Lower Byte Data Input/Output
DQ <sub>9</sub> to DQ <sub>16</sub>	Upper Byte Data Input/Output
V <sub>DD</sub>	Power Supply
V <sub>SS</sub>	Ground
NC	No Connection

# MB82D01171A-80/80L/80LL/85/85L/85LL/90/90L/90LL

## ■ BLOCK DIAGRAM



# MB82D01171A-80/80L/80LL/85/85L/85LL/90/90L/90LL

## ■ FUNCTION TRUTH TABLE \*1

Mode	$\overline{CE1}$	CE2	$\overline{WE}$	$\overline{OE}$	$\overline{LB}$	$\overline{UB}$	DQ <sub>1</sub> to DQ <sub>8</sub>	DQ <sub>9</sub> to DQ <sub>16</sub>	I <sub>DD</sub>	Data Retention	
Power Down *2	X	L	X	X	X	X	High-Z	High-Z	I <sub>DDP</sub>	No	
Standby (Deselect)	H	H	X	X	X	X	High-Z	High-Z	I <sub>DDs</sub>	Yes	
Output Disable*3	L		H	H	X	X	High-Z	High-Z	I <sub>DDA</sub>		
Read*4				L	X	X	Output Valid	Output Valid			
Write			L	L	H	L	L	Input Valid			Input Valid
Write (Lower Byte)						L	H	Input Valid			Invalid
Write (Upper Byte)						H	L	Invalid			Input Valid

\*1 : V = Valid, L = Logic Low, H = Logic High, X = either "L" or "H", High-Z = High Impedance

\*2 : Power Down mode can be entered from Standby state and all DQ pins are in High-Z state.

\*3 : Output Disable mode should not be kept longer than 1  $\mu$ s.

\*4 : Byte control at Read mode is not supported.

## ■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating		Unit
		Min	Max	
Voltage of V <sub>DD</sub> Supply Relative to V <sub>SS</sub>	V <sub>DD</sub>	-0.5	+3.6	V
Voltage at Any Pin Relative to V <sub>SS</sub>	V <sub>IN</sub>	-0.5	+3.6	V
	V <sub>OUT</sub>	-0.5	+3.6	V
Short Circuit Output Current	I <sub>OUT</sub>	-50	+50	mA
Storage Temperature	T <sub>STG</sub>	-55	+125	°C

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

## ■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Value		Unit
		Min	Max	
Supply Voltage *1	V <sub>DD</sub> (31)	3.1	3.5	V
	V <sub>DD</sub> (27)	2.7	3.1	V
	V <sub>DD</sub> (23)	2.3	2.7	V
	V <sub>SS</sub>	0	0	V
High Level Input Voltage *1, *2	V <sub>IH</sub> (31)	2.6	V <sub>DD</sub> + 0.3 and ≤ 3.6	V
	V <sub>IH</sub> (27)	2.2	V <sub>DD</sub> + 0.3	V
	V <sub>IH</sub> (23)	2.0	V <sub>DD</sub> + 0.3	V
Low Level Input Voltage *1, *2	V <sub>IL</sub> (31)	-0.3	0.5	V
	V <sub>IL</sub> (27)	-0.3	0.5	V
	V <sub>IL</sub> (23)	-0.3	0.4	V
Ambient Temperature	T <sub>A</sub>	-30	85	°C

\*1 : All voltages are referenced to V<sub>SS</sub>.

\*2 : Minimum DC voltage on input or I/O pins are -0.3 V. During voltage transitions, inputs may undershoot V<sub>SS</sub> to -1.0 V for periods of up to 5 ns. Maximum DC voltage on input and I/O pins are V<sub>DD</sub> + 0.3 V.

During voltage transitions, inputs may positive overshoot to V<sub>DD</sub> + 1.0 V for periods of up to 5 ns.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

# MB82D01171A-80/80L/80LL/85/85L/85LL/90/90L/90LL

## PIN CAPACITANCE

(f = 1.0 MHz, T<sub>A</sub> = +25 °C)

Parameter	Symbol	Conditions	Value			Unit
			Min	Typ	Max	
Address Input Capacitance	C <sub>IN1</sub>	V <sub>IN</sub> = 0 V	—	—	5	pF
Control Input Capacitance	C <sub>IN2</sub>	V <sub>IN</sub> = 0 V	—	—	5	pF
Data Input/Output Capacitance	C <sub>IO</sub>	V <sub>IO</sub> = 0 V	—	—	8	pF

## ELECTRICAL CHARACTERISTICS

### 1. DC Characteristics

Parameter	Symbol	Conditions	Value		Unit	
			Min	Max		
Input Leakage Current	I <sub>LI</sub>	V <sub>SS</sub> ≤ V <sub>IN</sub> ≤ V <sub>DD</sub>	-1.0	+1.0	μA	
Output Leakage Current	I <sub>LO</sub>	0 V ≤ V <sub>OUT</sub> ≤ V <sub>DD</sub> , Output Disable	-1.0	+1.0	μA	
Output High Voltage Level	V <sub>OH(31)</sub>	V <sub>DD</sub> = V <sub>DD(31)</sub> , I <sub>OH</sub> = -0.5 mA	2.4	—	V	
	V <sub>OH(27)</sub>	V <sub>DD</sub> = V <sub>DD(27)</sub> , I <sub>OH</sub> = -0.5 mA	2.25	—	V	
	V <sub>OH(23)</sub>	V <sub>DD</sub> = V <sub>DD(23)</sub> , I <sub>OH</sub> = -0.5 mA	1.8	—	V	
Output Low Voltage Level	V <sub>OL</sub>	I <sub>OL</sub> = 1 mA	—	0.4	V	
V <sub>DD</sub> Power Down Current	I <sub>DDP</sub>	V <sub>DD</sub> = V <sub>DD(31)</sub> Max, V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> , CE2 ≤ 0.2 V	—	20	μA	
		V <sub>DD</sub> = V <sub>DD(27, 23)</sub> Max, V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> , CE2 ≤ 0.2 V	—	10	μA	
V <sub>DD</sub> Standby Current	L Version LL Version	I <sub>DDS</sub>	V <sub>DD</sub> = V <sub>DD(31)</sub> Max, V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> CE1 = CE2 = V <sub>IH</sub> , I <sub>OUT</sub> = 0 mA	—	5.5	mA
				—	2.0	
				—	1.5	
	L Version LL Version	I <sub>DDS</sub>	V <sub>DD</sub> = V <sub>DD(27, 23)</sub> Max, V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> CE1 = CE2 = V <sub>IH</sub> , I <sub>OUT</sub> = 0 mA	—	5	mA
				—	1.5	
				—	1	
	L Version LL Version	I <sub>DDS1</sub>	V <sub>DD</sub> = V <sub>DD(31)</sub> Max, V <sub>IN</sub> ≤ 0.2 V or V <sub>IN</sub> ≥ V <sub>DD</sub> - 0.2 V, CE1 = CE2 ≥ V <sub>DD</sub> - 0.2 V, I <sub>OUT</sub> = 0 mA	—	250	μA
				—	150	
				—	120	
	L Version LL Version	I <sub>DDS1</sub>	V <sub>DD</sub> = V <sub>DD(27, 23)</sub> Max, V <sub>IN</sub> ≤ 0.2 V or V <sub>IN</sub> ≥ V <sub>DD</sub> - 0.2 V, CE1 = CE2 ≥ V <sub>DD</sub> - 0.2 V, I <sub>OUT</sub> = 0 mA	—	200	μA
				—	100	
				—	70	

(Continued)

# MB82D01171A-80/80L/80LL/85/85L/85LL/90/90L/90LL

(Continued)

Parameter	Symbol	Conditions	Value		Unit
			Min	Max	
V <sub>DD</sub> Active Current	I <sub>DDA1</sub>	V <sub>DD(31)</sub> = V <sub>DD</sub> Max, V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> , $\overline{CE1} = V_{IL}$ and CE2 = V <sub>IH</sub> , I <sub>OUT</sub> = 0 mA	—	25	mA
		V <sub>DD(27, 23)</sub> = V <sub>DD</sub> Max, V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> , $\overline{CE1} = V_{IL}$ and CE2 = V <sub>IH</sub> , I <sub>OUT</sub> = 0 mA		20	
	I <sub>DDA2</sub>	V <sub>DD(31)</sub> = V <sub>DD</sub> Max, V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> , $\overline{CE1} = V_{IL}$ and CE2 = V <sub>IH</sub> , I <sub>OUT</sub> = 0 mA	—	4.0	mA
		V <sub>DD(27, 23)</sub> = V <sub>DD</sub> Max, V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> , $\overline{CE1} = V_{IL}$ and CE2 = V <sub>IH</sub> , I <sub>OUT</sub> = 0 mA		3.0	

- Notes:
- All voltages are referenced to V<sub>SS</sub>.
  - DC Characteristics are measured after following POWER-UP timing.
  - I<sub>OUT</sub> depends on the output load conditions.



## 2. AC Characteristics

### (1) Read Operation

Parameter	Symbol	-80/-80L/ -80LL		-85/-85L/ -85LL		-90/-90L/ -90LL		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Read Cycle Time	$t_{RC}$	90	—	90	—	90	—	ns	
Chip Enable Access Time	$t_{CE}$	—	80	—	85	—	90	ns	*1, *3
Output Enable Access Time	$t_{OE}$	—	45	—	45	—	45	ns	*1
Address Access Time	$t_{AA}$	—	80	—	85	—	90	ns	*1, *4
Output Data Hold Time	$t_{OH}$	5	—	5	—	5	—	ns	*1
$\overline{CE1}$ Low to Output Low-Z	$t_{CLZ}$	5	—	5	—	5	—	ns	*2
$\overline{OE}$ Low to Output Low-Z	$t_{OLZ}$	0	—	0	—	0	—	ns	*2
$\overline{CE1}$ High to Output High-Z	$t_{CHZ}$	—	30	—	30	—	30	ns	*2
$\overline{OE}$ High to Output High-Z	$t_{OHZ}$	—	25	—	25	—	25	ns	*2
Address Setup Time to $\overline{CE1}$ Low	$t_{ASC}$	-5	—	-5	—	-5	—	ns	*5
Address Setup Time to $\overline{OE}$ Low	$t_{ASO}$	45	—	45	—	45	—	ns	*3, *6
	$t_{ASO[ABS]}$	10	—	10	—	10	—	ns	*7
Address Invalid Time	$t_{AX}$	—	5	—	5	—	5	ns	*4
$\overline{CE1}$ Low to Address Hold Time	$t_{CLAH}$	90	—	90	—	90	—	ns	*4
$\overline{OE}$ Low to Address Hold Time	$t_{OLAH}$	45	—	45	—	45	—	ns	*4, *8
$\overline{CE1}$ High to Address Hold Time	$t_{CHAH}$	-5	—	-5	—	-5	—	ns	
$\overline{OE}$ High to Address Hold Time	$t_{OHAH}$	-5	—	-5	—	-5	—	ns	
$\overline{CE1}$ Low to $\overline{OE}$ Low Delay Time	$t_{CLOL}$	45	1000	45	1000	45	1000	ns	*3, *6, *8, *9
$\overline{OE}$ Low to $\overline{CE1}$ High Delay Time	$t_{OLCH}$	45	—	45	—	45	—	ns	*8
$\overline{CE1}$ High Pulse Width	$t_{CP}$	20	—	20	—	20	—	ns	
$\overline{OE}$ High Pulse Width	$t_{OP}$	45	1000	45	1000	45	1000	ns	*6, *8, *9
	$t_{OP[ABS]}$	20	—	20	—	20	—	ns	*7

\*1: The output load is 30 pF.

\*2: The output load is 5 pF.

\*3: The  $t_{CE}$  is applicable if  $\overline{OE}$  is brought to Low before  $\overline{CE1}$  goes Low and is also applicable if actual value of both or either  $t_{ASO}$  or  $t_{CLOL}$  is shorter than specified value.

\*4: Applicable only to  $A_0$  and  $A_1$  when both  $\overline{CE1}$  and  $\overline{OE}$  are kept at Low for the address access.

\*5: Applicable if  $\overline{OE}$  is brought to Low before  $\overline{CE1}$  goes Low.

\*6: The  $t_{ASO}$ ,  $t_{CLOL}$  (Min) and  $t_{OP}$  (Min) are reference values when the access time is determined by  $t_{OE}$ .

If actual value of each parameter is shorter than specified minimum value,  $t_{OE}$  become longer by the amount of subtraction actual value from specified minimum value.

For example, if actual  $t_{ASO}$ ,  $t_{ASO}$  (actual), is shorter than specified minimum value,  $t_{ASO}$  (Min), during  $\overline{OE}$  control access (i.e.,  $\overline{CE1}$  stays Low), the  $t_{OE}$  become  $t_{OE}$  (Max) +  $t_{ASO}$  (Min) -  $t_{ASO}$  (actual).

\*7: The  $t_{ASO[ABS]}$  and  $t_{OP[ABS]}$  is the absolute minimum value during  $\overline{OE}$  control access.

\*8: If actual value of either  $t_{CLOL}$  or  $t_{OP}$  is shorter than specified minimum value, both  $t_{OLAH}$  and  $t_{OLCH}$  become  $t_{RC}$  (Min) -  $t_{CLOL}$  (actual) or  $t_{RC}$  (Min) -  $t_{OP}$  (actual).

\*9: Maximum value is applicable if  $\overline{CE1}$  is kept at Low.

## (2) Write Operation

Parameter	Symbol	-80/-80L/ -80LL		-85/-85L/ -85LL		-90/-90L/ -90LL		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Write Cycle Time	$t_{WC}$	90	—	90	—	90	—	ns	*1
Address Setup Time	$t_{AS}$	0	—	0	—	0	—	ns	*2
Address Hold Time	$t_{AH}$	45	—	45	—	45	—	ns	*2
$\overline{CE1}$ Write Setup Time	$t_{CS}$	0	1000	0	1000	0	1000	ns	
$\overline{CE1}$ Write Hold Time	$t_{CH}$	0	1000	0	1000	0	1000	ns	
$\overline{WE}$ Setup Time	$t_{WS}$	0	—	0	—	0	—	ns	
$\overline{WE}$ Hold Time	$t_{WH}$	0	—	0	—	0	—	ns	
$\overline{LB}$ and $\overline{UB}$ Setup Time	$t_{BS}$	-5	—	-5	—	-5	—	ns	
$\overline{LB}$ and $\overline{UB}$ Hold Time	$t_{BH}$	-5	—	-5	—	-5	—	ns	
$\overline{OE}$ Setup Time	$t_{OES}$	0	1000	0	1000	0	1000	ns	*3
$\overline{OE}$ Hold Time	$t_{OEH}$	45	1000	45	1000	45	1000	ns	*3, *4
	$t_{OEH[ABS]}$	20	—	20	—	20	—	ns	*5
$\overline{OE}$ High to $\overline{CE1}$ Low Setup Time	$t_{OHCL}$	-3	—	-3	—	-3	—	ns	*6
Address Hold Time to $\overline{OE}$ High	$t_{OHAH}$	0	—	0	—	0	—	ns	*7
$\overline{CE1}$ Write Pulse Width	$t_{CW}$	60	—	60	—	60	—	ns	*1, *8
$\overline{WE}$ Write Pulse Width	$t_{WP}$	60	—	60	—	60	—	ns	*1, *8
$\overline{CE1}$ Write Recovery Time	$t_{WRC}$	15	—	15	—	15	—	ns	*1, *9
$\overline{WE}$ Write Recovery Time	$t_{WR}$	15	1000	15	1000	15	1000	ns	*1, *3, *9
Data Setup Time	$t_{DS}$	20	—	20	—	20	—	ns	
Data Hold Time	$t_{DH}$	0	—	0	—	0	—	ns	
$\overline{CE1}$ High Pulse Width	$t_{CP}$	20	—	20	—	20	—	ns	*9

\*1: Minimum value must be equal or greater than the sum of actual  $t_{CW}$  (or  $t_{WP}$ ) and  $t_{WRC}$  (or  $t_{WR}$ ) .

\*2: New write address is valid from either  $\overline{CE1}$  or  $\overline{WE}$  is brought to High.

\*3: Maximum value is applicable if  $\overline{CE1}$  is kept at Low and both  $\overline{WE}$  and  $\overline{OE}$  are kept at High.

\*4: The  $t_{OEH}$  is specified from end of  $t_{WC}$  (Min) and is a reference value when access time is determined by  $t_{OE}$ .

If actual value is shorter than specified minimum value,  $t_{OE}$  become longer by the amount of subtracting actual value from specified minimum value.

\*5: The  $t_{OEH[ABS]}$  is the absolute minimum value if write cycle is terminated by  $\overline{WE}$  and  $\overline{CE1}$  stays Low.

\*6:  $t_{OHCL}$  (Min) must be satisfied if read operation is not performed prior to write operation.

In case  $\overline{OE}$  is disabled after  $t_{OHCL}$  (Min) ,  $\overline{WE}$  Low must be asserted after  $t_{RC}$  (Min) from  $\overline{CE1}$  Low.

In other words, read operation is initiated if  $t_{OHCL}$  (Min) is not satisfied.

\*7: Applicable if  $\overline{CE1}$  stays Low after read operation.

\*8:  $t_{CW}$  and  $t_{WP}$  is applicable if write operation is initiated by  $\overline{CE1}$  and  $\overline{WE}$ , respectively.

\*9:  $t_{WRC}$  and  $t_{WR}$  is applicable if write operation is terminated by  $\overline{CE1}$  and  $\overline{WE}$ , respectively.

The  $t_{WR}$  (Min) can be ignored if  $\overline{CE1}$  is brought to High together or after  $\overline{WE}$  is brought to High.

In such case, the  $t_{CP}$  (Min) must be satisfied.

### (3) Power Down Parameters

Parameter	Symbol	Value		Unit	Note
		Min	Max		
CE2 Low Setup Time for Power Down Entry	t <sub>CSP</sub>	10	—	ns	
CE2 Low Hold Time after Power Down Entry	t <sub>C2LP</sub>	100	—	ns	
$\overline{CE1}$ High Hold Time following CE2 High after Power Down Exit	t <sub>CHH</sub>	350	—	μs	
$\overline{CE1}$ High Setup Time following CE2 High after Power Down Exit	t <sub>CHS</sub>	10	—	ns	

### (4) Other Timing Parameters

Parameter	Symbol	Value		Unit	Note
		Min	Max		
$\overline{CE1}$ High to $\overline{OE}$ Invalid Time for Standby Entry	t <sub>CHOX</sub>	20	—	ns	
$\overline{CE1}$ High to $\overline{WE}$ Invalid Time for Standby Entry	t <sub>CHWX</sub>	20	—	ns	*1
CE2 Low Hold Time after Power-up	t <sub>C2LH</sub>	50	—	μs	*2
CE2 High Hold Time after Power-up	t <sub>C2HL</sub>	50	—	μs	*3
$\overline{CE1}$ High Hold Time following CE2 High after Power-up	t <sub>CHH</sub>	350	—	μs	*2
Input Transition Time	t <sub>T</sub>	1	25	ns	*4

\*1: It may write some data into any address location if t<sub>CHWX</sub> is not satisfied.

\*2: Must satisfy t<sub>CHH</sub> (Min) after t<sub>C2LH</sub> (Min) .

\*3: Requires Power Down mode entry and exit after t<sub>C2HL</sub>.

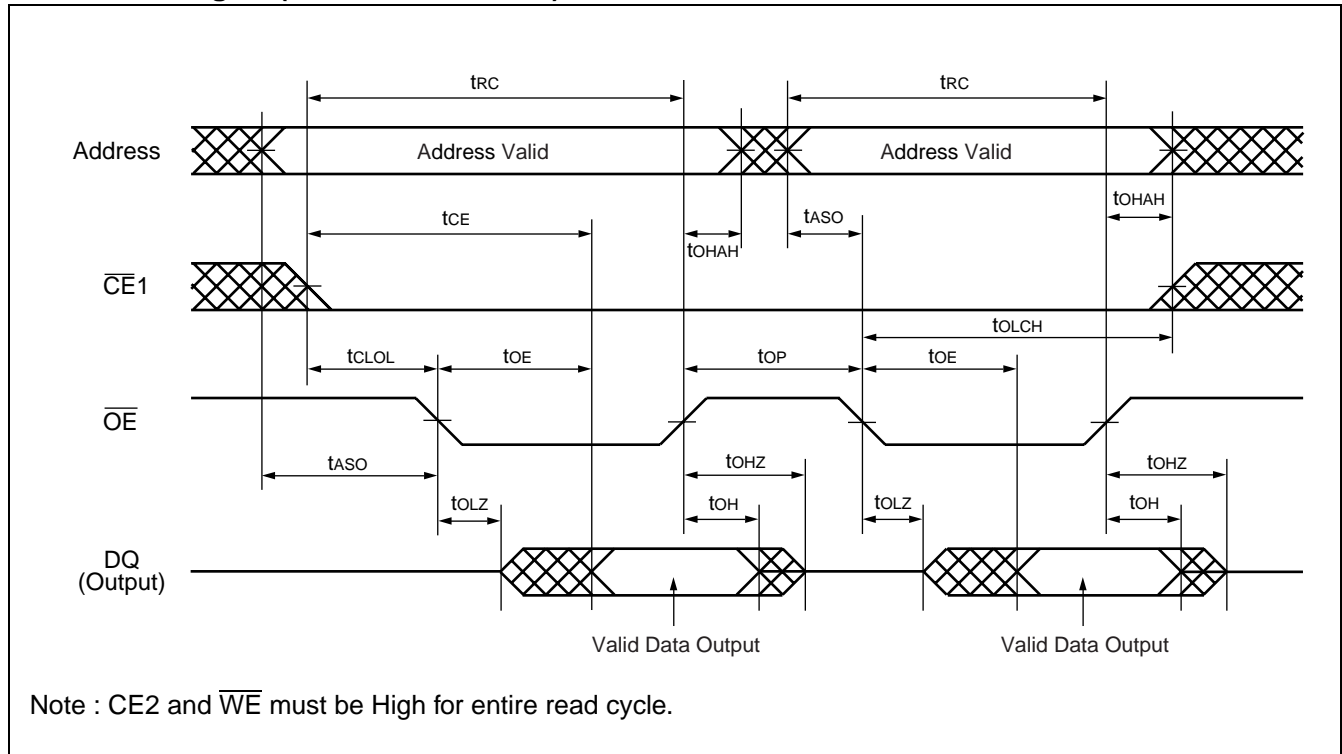
\*4: The Input Transition Time (t<sub>T</sub>) at AC testing is 5 ns as shown in below. If actual t<sub>T</sub> is longer than 5 ns, it may violate some timing parameters of AC specification.

### (5) AC Test Conditions

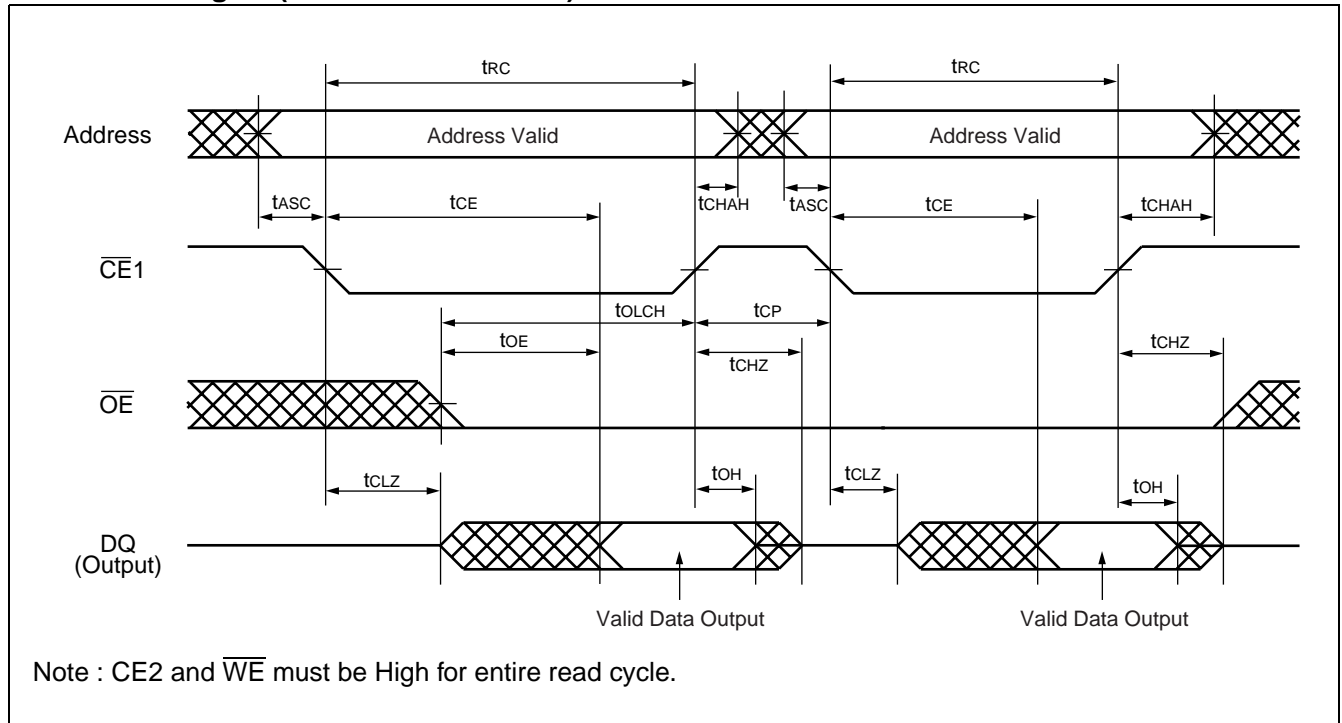
Parameter	Symbol	Conditions	Measured Value	Unit	Note
Input High Level	V <sub>IH</sub>	V <sub>DD</sub> = 3.1 V to 3.5 V	2.6	V	
		V <sub>DD</sub> = 2.7 V to 3.1 V	2.3	V	
		V <sub>DD</sub> = 2.3 V to 2.7 V	2.0	V	
Input Low Level	V <sub>IL</sub>	V <sub>DD</sub> = 3.1 V to 3.5 V	0.5	V	
		V <sub>DD</sub> = 2.7 V to 3.1 V	0.5	V	
		V <sub>DD</sub> = 2.3 V to 2.7 V	0.4	V	
Input Timing Measurement Level	V <sub>REF</sub>	V <sub>DD</sub> = 3.1 V to 3.5 V	1.5	V	
		V <sub>DD</sub> = 2.7 V to 3.1 V	1.3	V	
		V <sub>DD</sub> = 2.3 V to 2.7 V	1.1	V	
Input Transition Time	t <sub>T</sub>	Between V <sub>IL</sub> and V <sub>IH</sub>	5	ns	

## ■ TIMING DIAGRAM

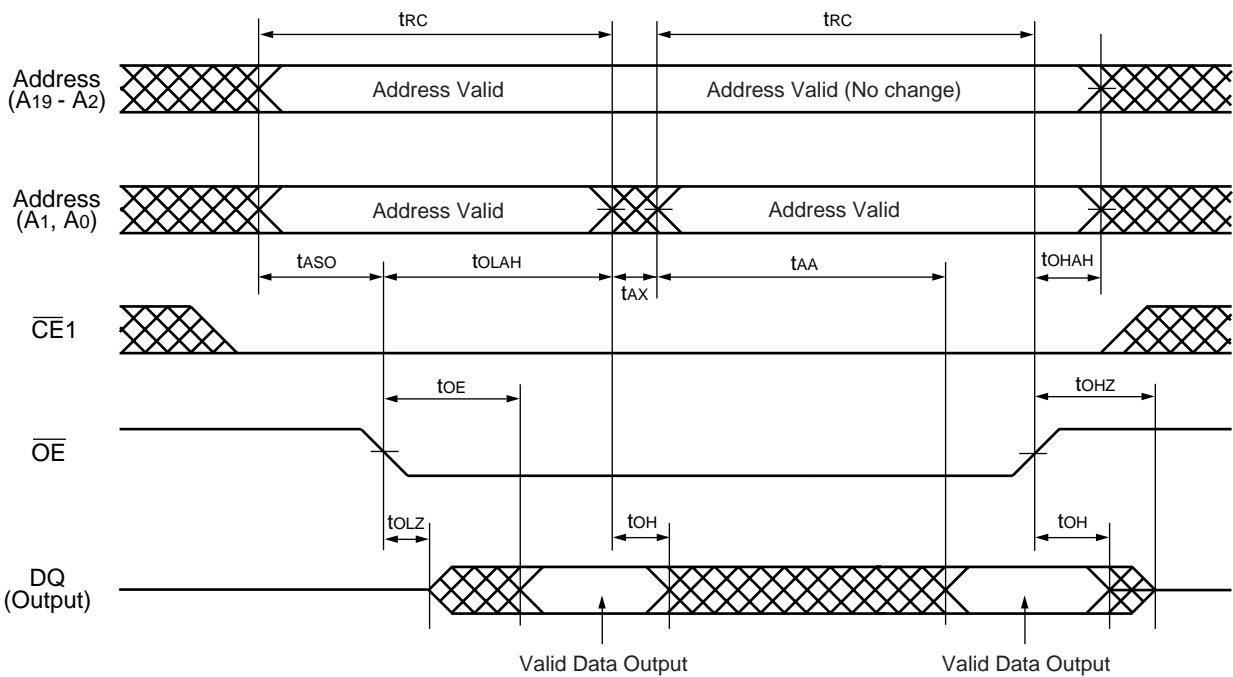
### 1. READ Timing #1 ( $\overline{OE}$ Control Access)



### 2. READ Timing #2 ( $\overline{CE1}$ Control Access)

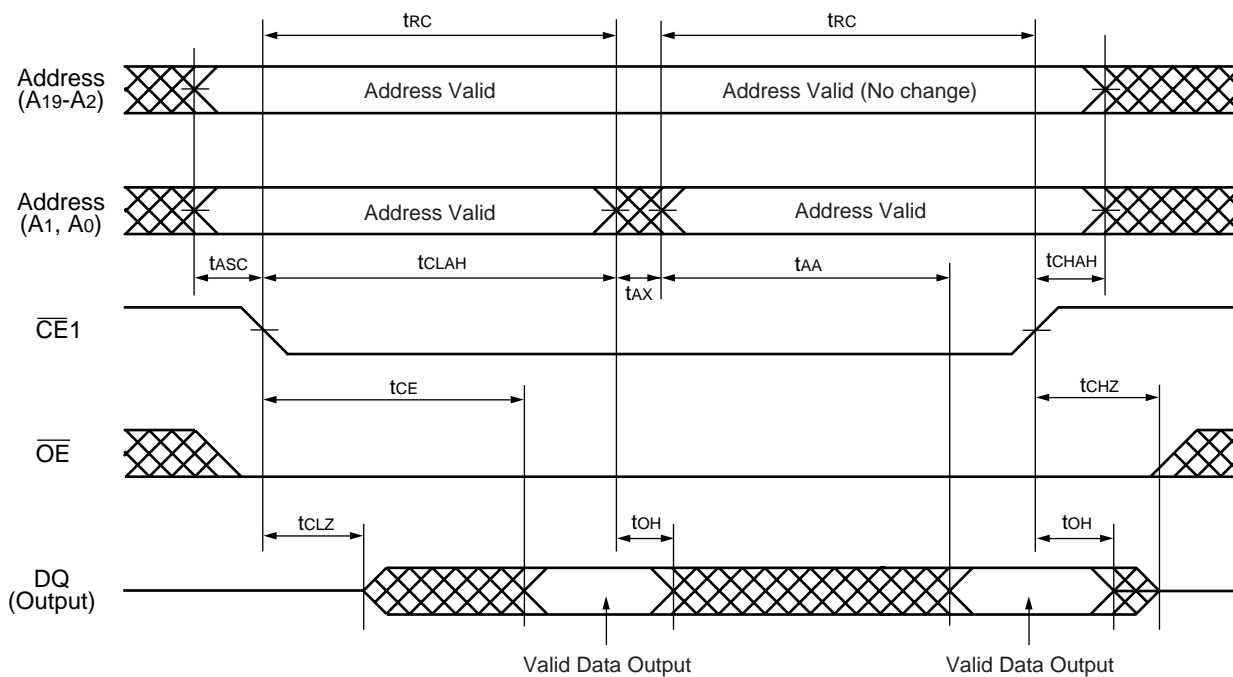


### 3. READ Timing #3 (Address Access after $\overline{OE}$ Control Access)



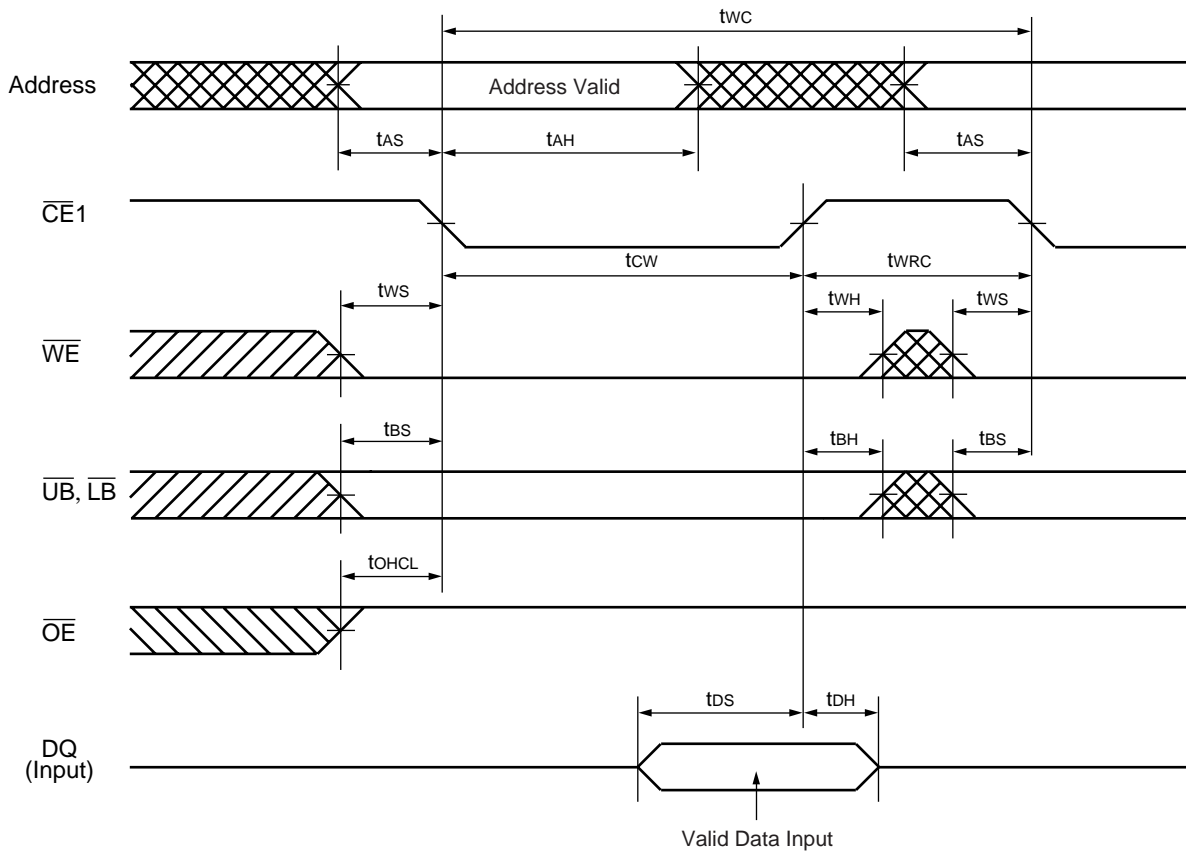
Note :  $\overline{CE2}$  and  $\overline{WE}$  must be High for entire read cycle.

### 4. READ Timing #4 (Address Access after $\overline{CE1}$ Control Access)



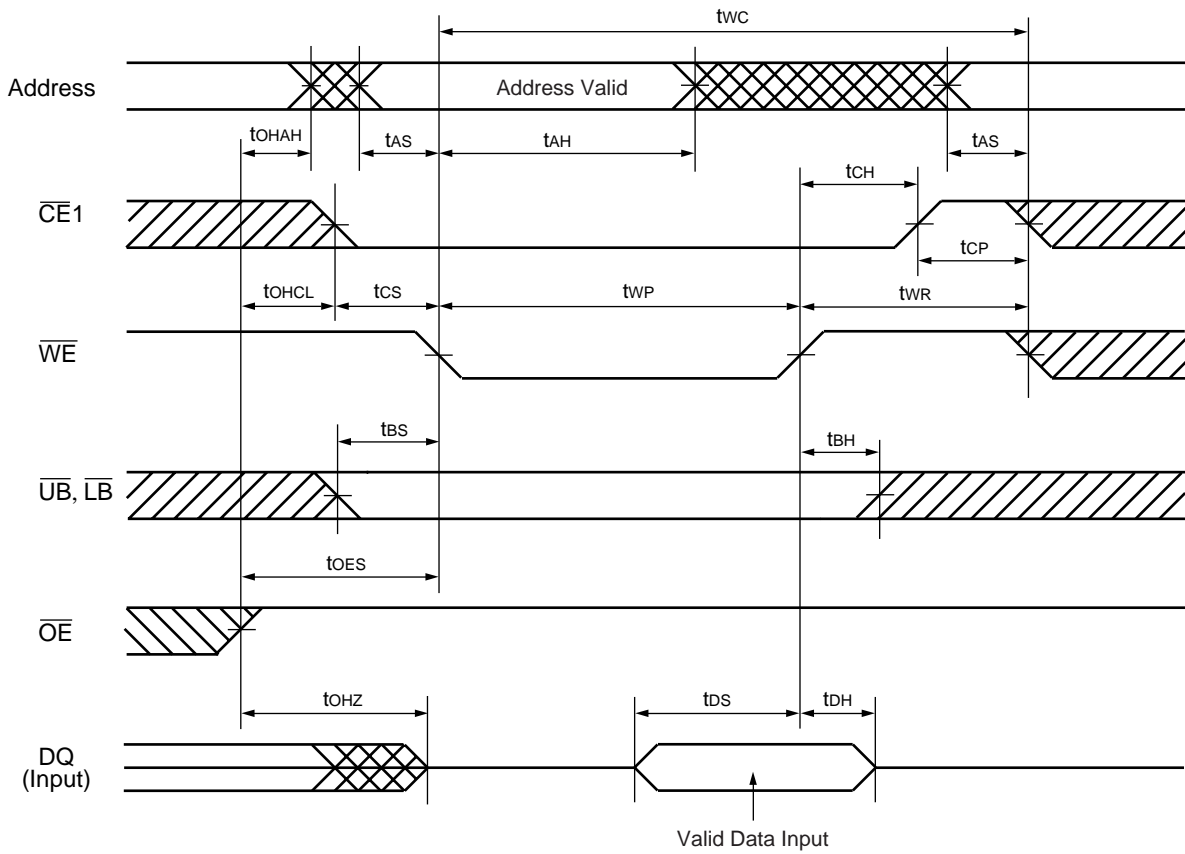
Note :  $\overline{CE2}$  and  $\overline{WE}$  must be High for entire read cycle.

## 5. WRITE Timing #1 ( $\overline{CE1}$ Control)



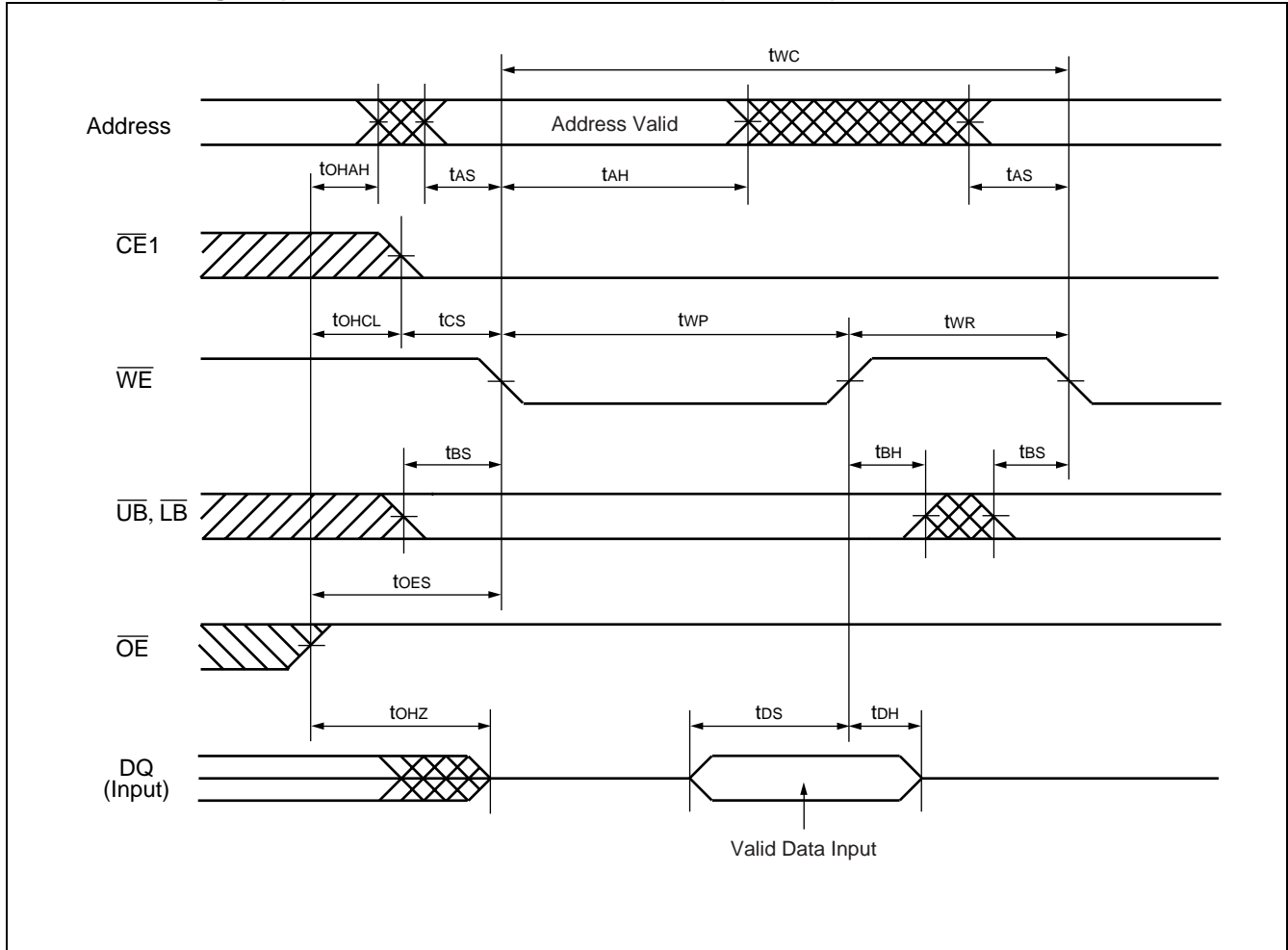
Note :  $\overline{CE2}$  must be High for write cycle.

## 6. WRITE Timing #2-1 ( $\overline{WE}$ Control, Single Write Operation)



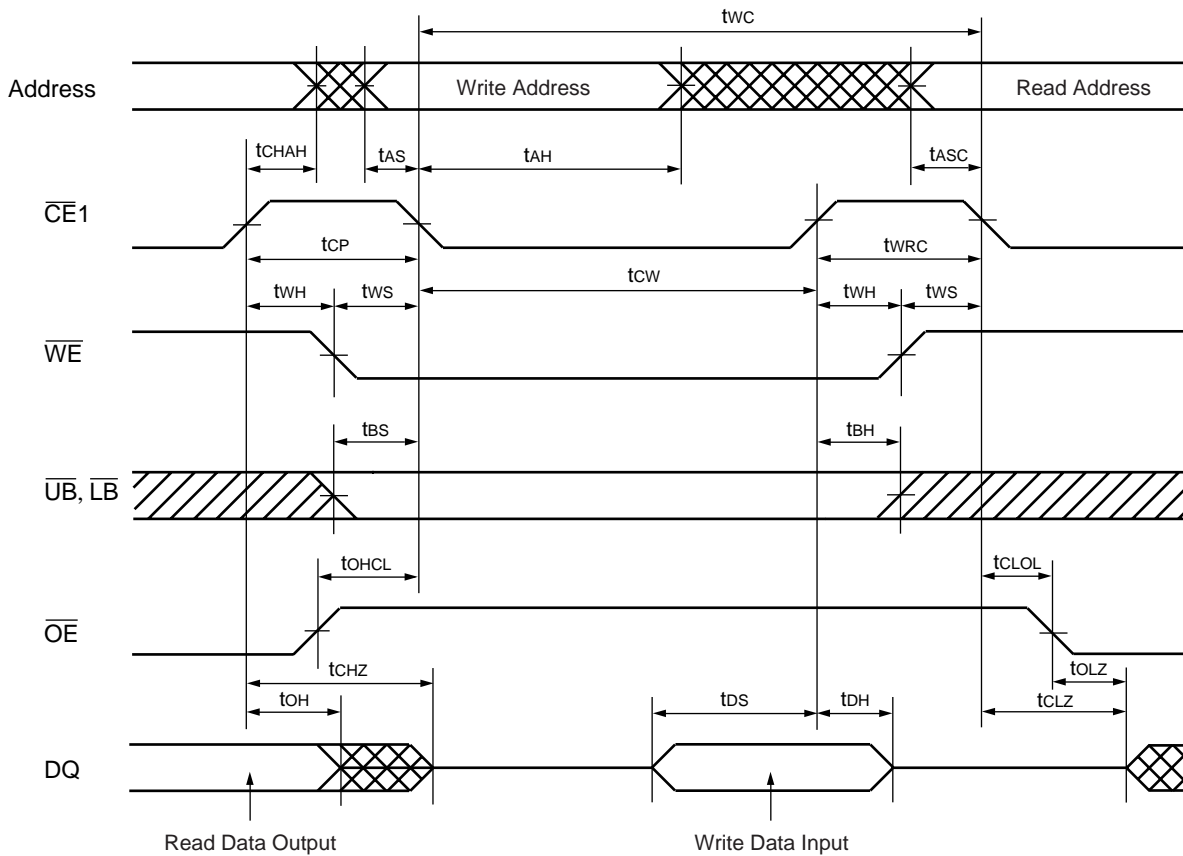
Note : CE2 must be High for write cycle.

## 7. WRITE Timing #2 ( $\overline{\text{WE}}$ Control, Continuous Write Operation)



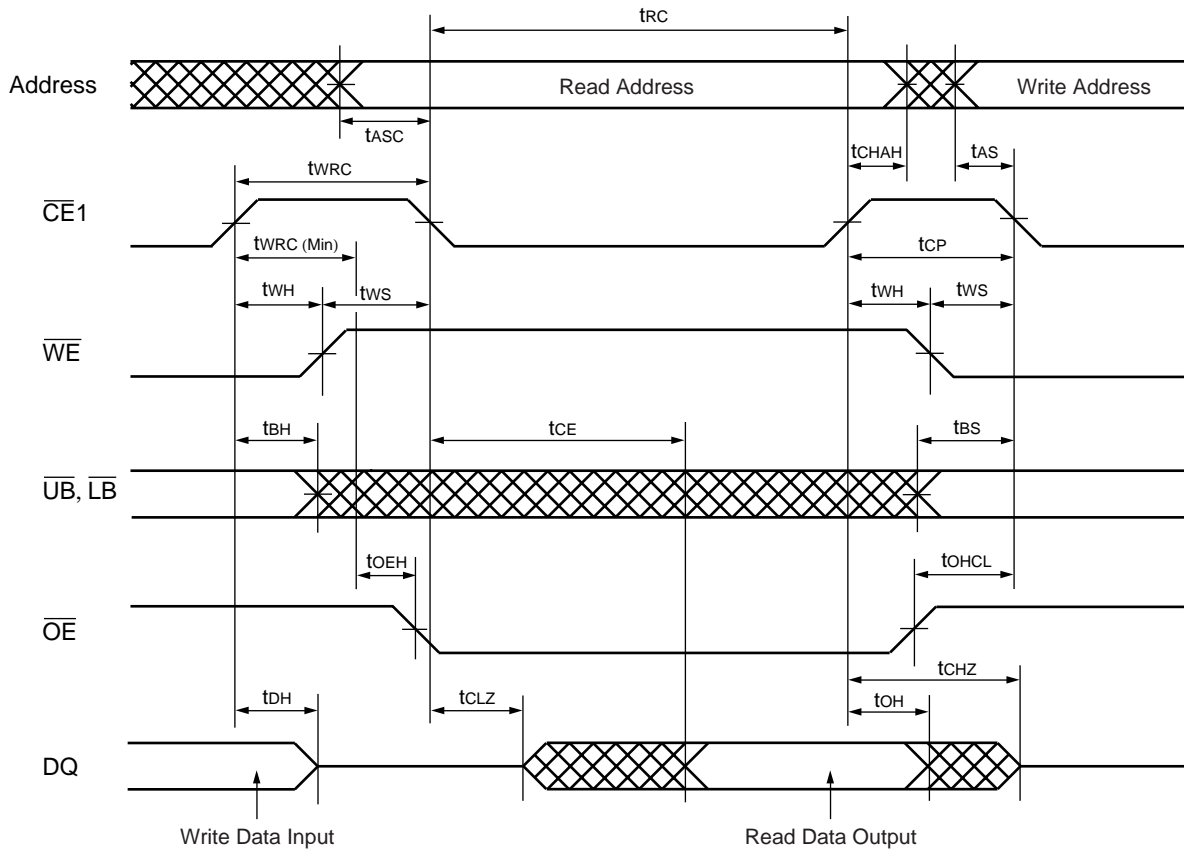


## 8. READ/WRITE Timing #1-1 ( $\overline{CE1}$ Control)



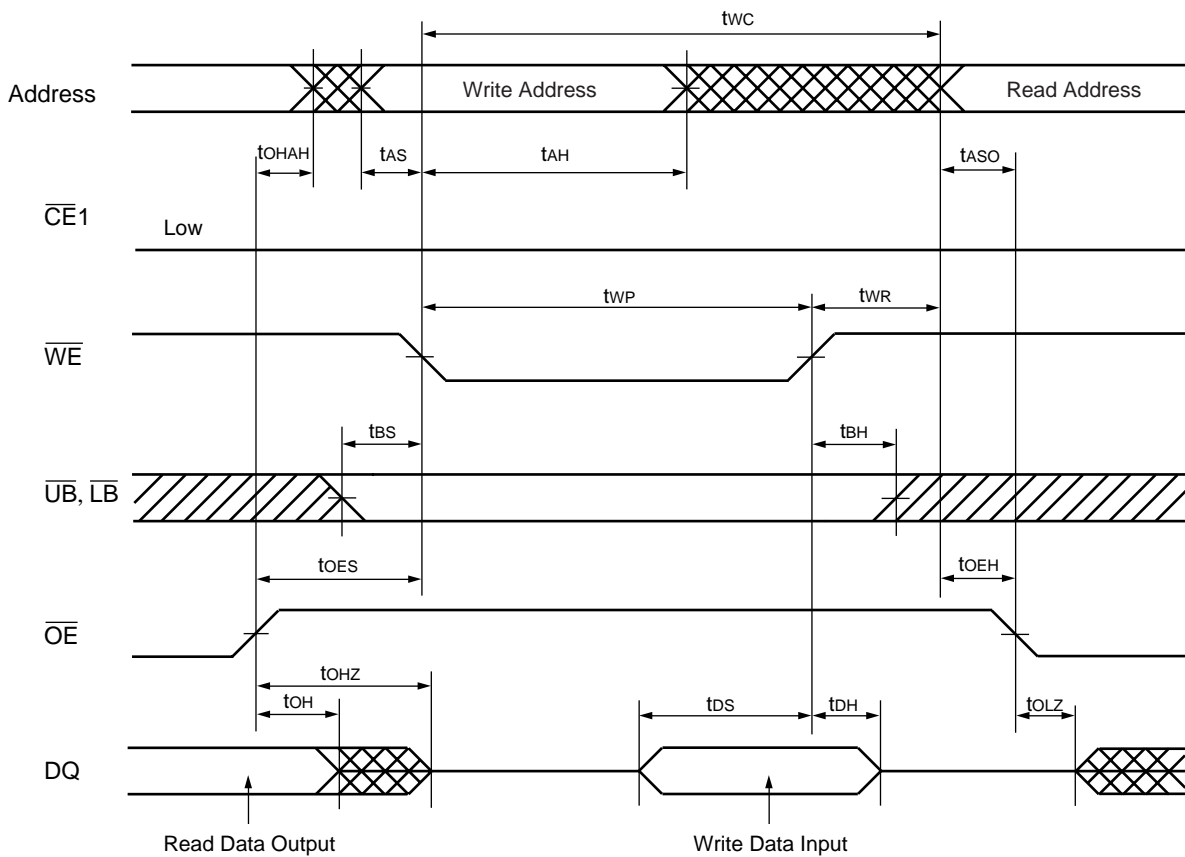
Note : Write address is valid from either  $\overline{CE1}$  or  $\overline{WE}$  of last falling edge.

## 9. READ/WRITE Timing #1-2 ( $\overline{CE1}$ Control)



Note : The  $t_{OEHL}$  is specified from the time satisfied both  $t_{WRC}$  and  $t_{WR}(\text{Min})$  .

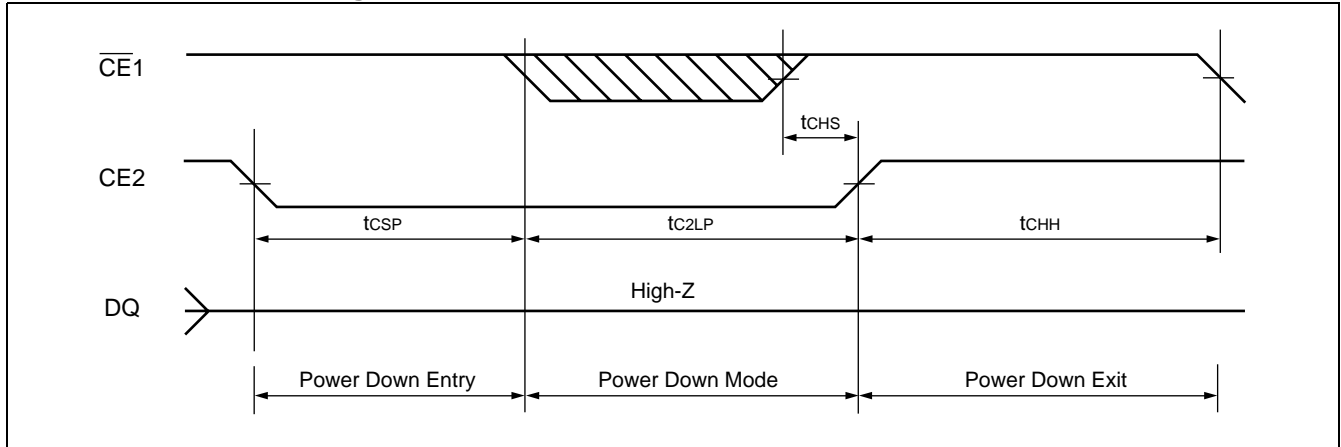
## 10. READ ( $\overline{OE}$ Control) /WRITE ( $\overline{WE}$ Control) Timing #2-1



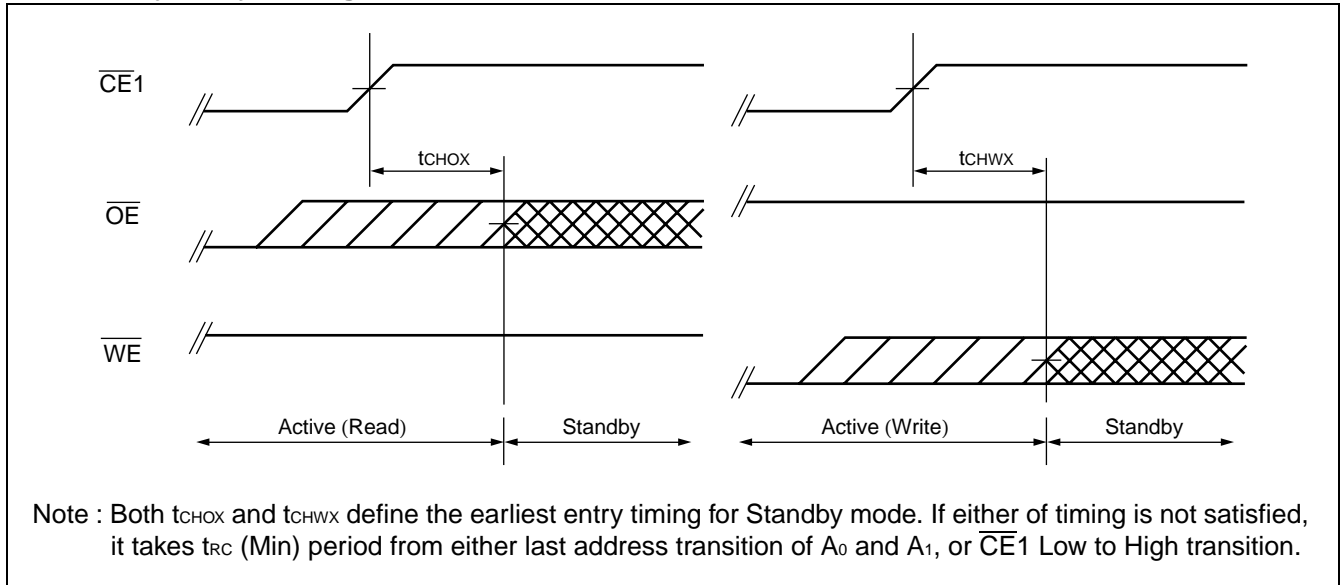
Note :  $\overline{CE1}$  can be tied to Low for  $\overline{WE}$  and  $\overline{OE}$  controlled operation.  
When  $\overline{CE1}$  is tied to Low, output is exclusively controlled by  $\overline{OE}$ .



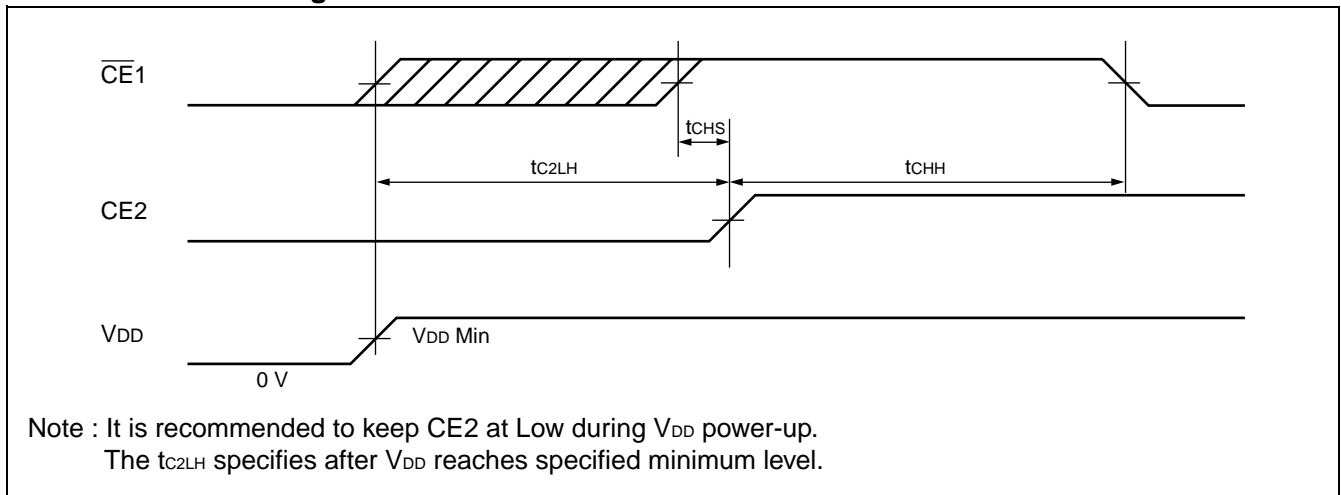
## 12. POWER DOWN Timing



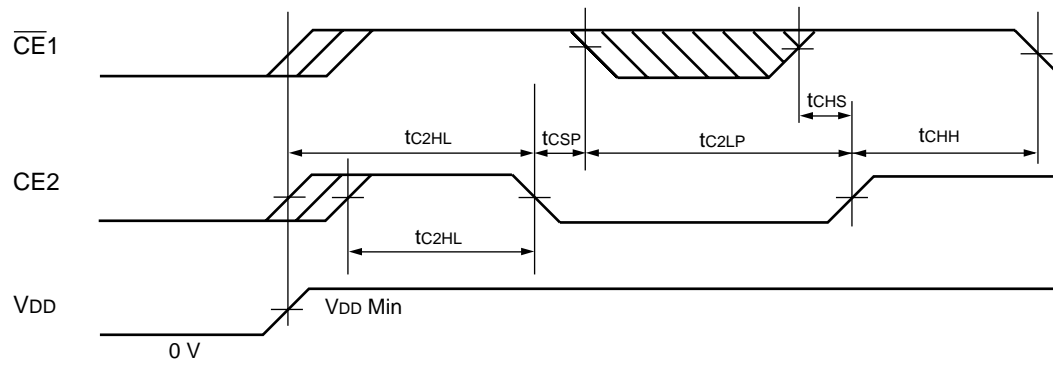
## 13. Standby Entry Timing after Read or Write



## 14. POWER-UP Timing 1



## 15. POWER-UP Timing 2



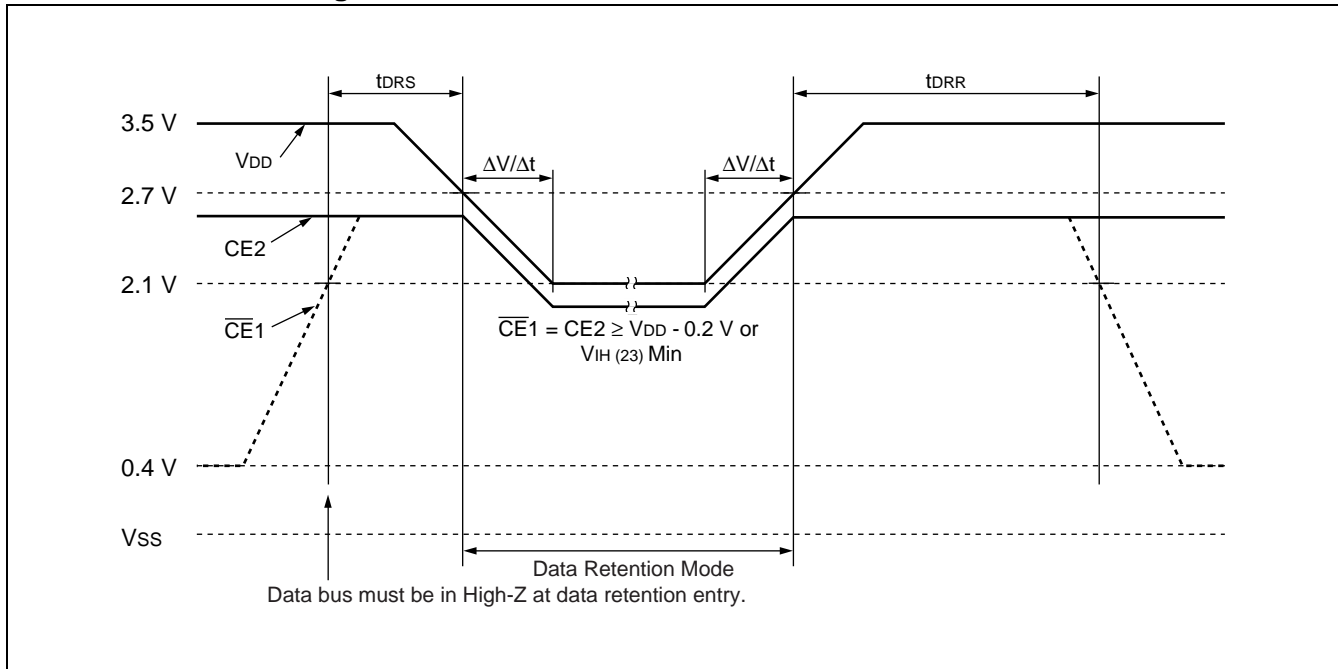
Note : The  $t_{C2HL}$  specifies from  $CE2$  Low to High transition after  $V_{DD}$  reaches specified minimum level.  $\overline{CE1}$  must be brought to High prior to or together with  $CE2$  Low to High transition.

## ■ DATA RETENTION

### 1. Low $V_{DD}$ Characteristics

Parameter	Symbol	Test Conditions	Value		Unit	
			Min	Max		
$V_{DD}$ Data Retention Supply Voltage	$V_{DR}$	$\overline{CE1} = CE2 \geq V_{DD} - 0.2 \text{ V}$ or, $\overline{CE1} = CE2 = V_{IH}$ ,	2.1	3.5	V	
$V_{DD}$ Data Retention Supply Current	L Version	$I_{DR}$	$V_{DD} = V_{DD}^{(23)}$ , $V_{IN} = V_{IH}^{(23)}$ or $V_{IL}$ $\overline{CE1} = CE2 = V_{IH}^{(23)}$ , $I_{OUT} = 0 \text{ mA}$	—	5	mA
				—	1.5	
	LL Version	$I_{DR1}$	$V_{DD} = V_{DD}^{(23)}$ , $V_{IN} \leq 0.2 \text{ V}$ or $V_{IN} \geq V_{DD} - 0.2 \text{ V}$ , $\overline{CE1} = CE2 \geq V_{DD} - 0.2 \text{ V}$ , $I_{OUT} = 0 \text{ mA}$	—	200	$\mu\text{A}$
				—	100	
			—	70		
Data Retention Setup Time	$t_{DRS}$	$V_{DD} = V_{DD}^{(27)}$ at data retention entry	0	—	ns	
Data Retention Recovery Time	$t_{DRR}$	$V_{DD} = V_{DD}^{(27)}$ after data retention	90	—	ns	
$V_{DD}$ Voltage Transition Time	$\Delta V/\Delta t$	—	0.5	—	V/ $\mu\text{s}$	

### 2. Data Retention Timing



# MB82D01171A-80/80L/80LL/85/85L/85LL/90/90L/90LL

## ■ ORDERING INFORMATION

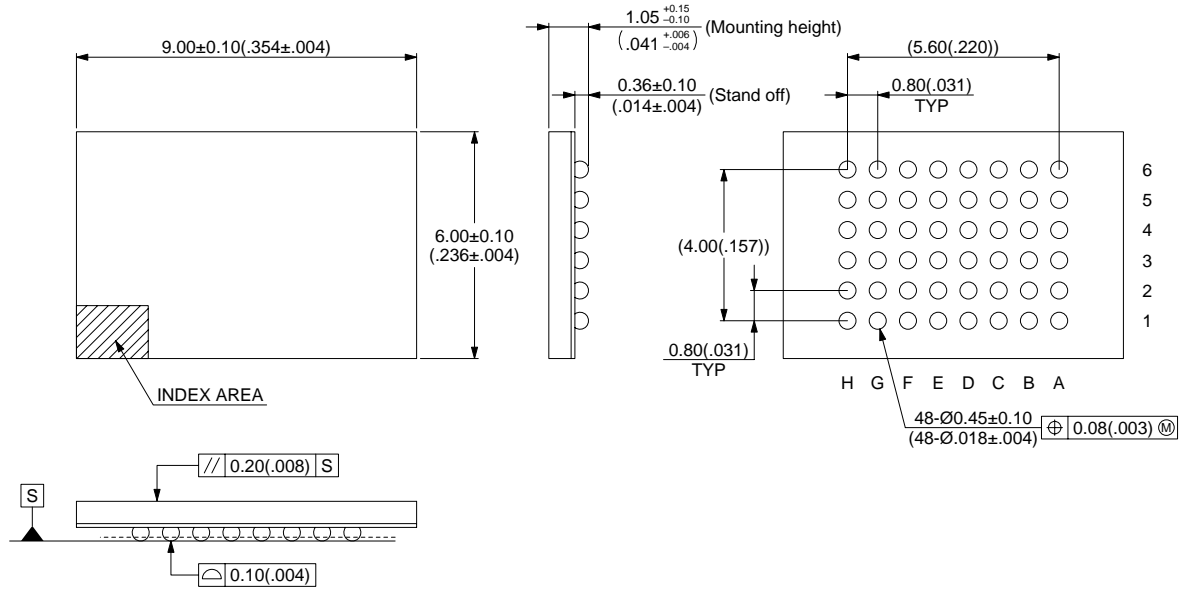
Part Number	Package	Remarks
MB82D01171A-80PBT	48-ball plastic FBGA 0.8 mm pitch (BGA-48P-M16)	$t_{CE} = 80$ ns Max, $I_{DDs1} = 200$ $\mu$ A Max Flash Compatible Package
MB82D01171A-80LPBT	48-ball plastic FBGA 0.8 mm pitch (BGA-48P-M16)	$t_{CE} = 80$ ns Max, $I_{DDs1} = 100$ $\mu$ A Max Flash Compatible Package
MB82D01171A-80LLPBT	48-ball plastic FBGA 0.8 mm pitch (BGA-48P-M16)	$t_{CE} = 80$ ns Max, $I_{DDs1} = 70$ $\mu$ A Max Flash Compatible Package
MB82D01171A-85PBT	48-ball plastic FBGA 0.8 mm pitch (BGA-48P-M16)	$t_{CE} = 85$ ns Max, $I_{DDs1} = 200$ $\mu$ A Max Flash Compatible Package
MB82D01171A-85LPBT	48-ball plastic FBGA 0.8 mm pitch (BGA-48P-M16)	$t_{CE} = 85$ ns Max, $I_{DDs1} = 100$ $\mu$ A Max Flash Compatible Package
MB82D01171A-85LLPBT	48-ball plastic FBGA 0.8 mm pitch (BGA-48P-M16)	$t_{CE} = 85$ ns Max, $I_{DDs1} = 70$ $\mu$ A Max Flash Compatible Package
MB82D01171A-90PBT	48-ball plastic FBGA 0.8 mm pitch (BGA-48P-M16)	$t_{CE} = 90$ ns Max, $I_{DDs1} = 200$ $\mu$ A Max Flash Compatible Package
MB82D01171A-90LPBT	48-ball plastic FBGA 0.8 mm pitch (BGA-48P-M16)	$t_{CE} = 90$ ns Max, $I_{DDs1} = 100$ $\mu$ A Max Flash Compatible Package
MB82D01171A-90LLPBT	48-ball plastic FBGA 0.8 mm pitch (BGA-48P-M16)	$t_{CE} = 90$ ns Max, $I_{DDs1} = 70$ $\mu$ A Max Flash Compatible Package
MB82D01171A-80PBN	48-ball plastic FBGA 0.75 mm pitch (BGA-48P-M18)	$t_{CE} = 80$ ns Max, $I_{DDs1} = 200$ $\mu$ A Max SRAM Compatible Package
MB82D01171A-80LPBN	48-ball plastic FBGA 0.75 mm pitch (BGA-48P-M18)	$t_{CE} = 80$ ns Max, $I_{DDs1} = 100$ $\mu$ A Max SRAM Compatible Package
MB82D01171A-80LLPBN	48-ball plastic FBGA 0.75 mm pitch (BGA-48P-M18)	$t_{CE} = 80$ ns Max, $I_{DDs1} = 70$ $\mu$ A Max SRAM Compatible Package
MB82D01171A-85PBN	48-ball plastic FBGA 0.75 mm pitch (BGA-48P-M18)	$t_{CE} = 85$ ns Max, $I_{DDs1} = 200$ $\mu$ A Max SRAM Compatible Package
MB82D01171A-85LPBN	48-ball plastic FBGA 0.75 mm pitch (BGA-48P-M18)	$t_{CE} = 85$ ns Max, $I_{DDs1} = 100$ $\mu$ A Max SRAM Compatible Package
MB82D01171A-85LLPBN	48-ball plastic FBGA 0.75 mm pitch (BGA-48P-M18)	$t_{CE} = 85$ ns Max, $I_{DDs1} = 70$ $\mu$ A Max SRAM Compatible Package
MB82D01171A-90PBN	48-ball plastic FBGA 0.75 mm pitch (BGA-48P-M18)	$t_{CE} = 90$ ns Max, $I_{DDs1} = 200$ $\mu$ A Max SRAM Compatible Package
MB82D01171A-90LPBN	48-ball plastic FBGA 0.75 mm pitch (BGA-48P-M18)	$t_{CE} = 90$ ns Max, $I_{DDs1} = 100$ $\mu$ A Max SRAM Compatible Package
MB82D01171A-90LLPBN	48-ball plastic FBGA 0.75 mm pitch (BGA-48P-M18)	$t_{CE} = 90$ ns Max, $I_{DDs1} = 70$ $\mu$ A Max SRAM Compatible Package



# MB82D01171A-80/80L/80LL/85/85L/85LL/90/90L/90LL

## ■ PACKAGE DIMENSIONS

48-ball plastic FBGA  
(BGA-48P-M16)



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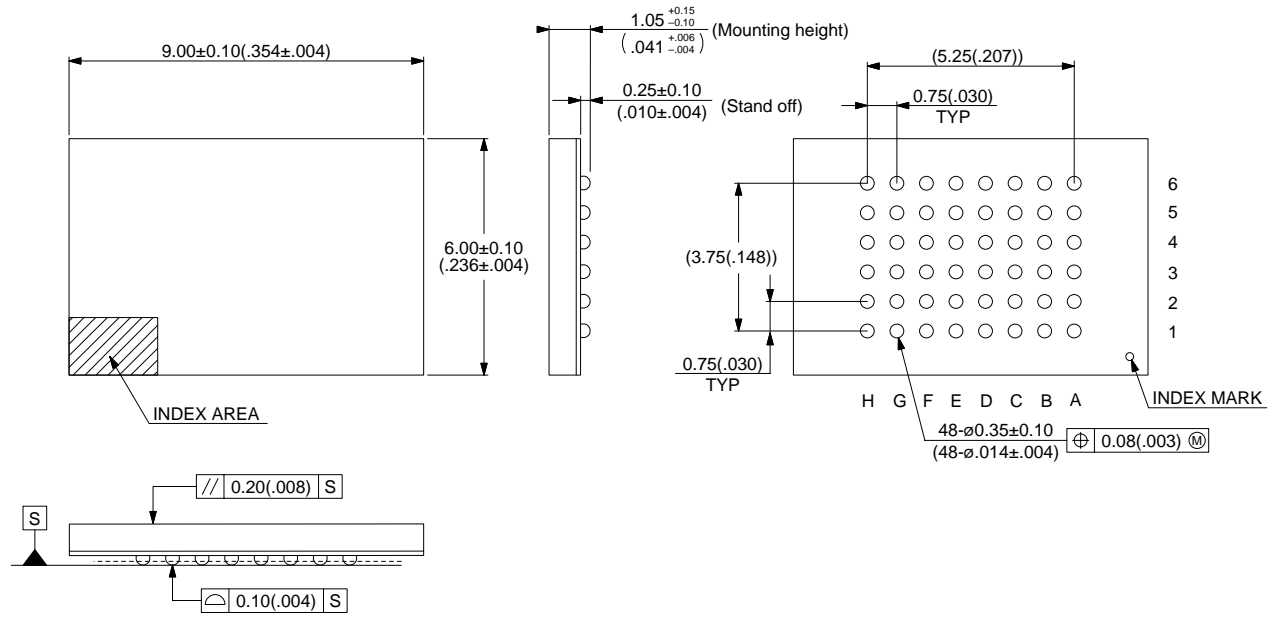
Dimensions in mm (inches)

(Continued)

# MB82D01171A-80/80L/80LL/85/85L/85LL/90/90L/90LL

(Continued)

48-ball plastic FBGA  
(BGA-48P-M18)



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Dimensions in mm (inches)

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